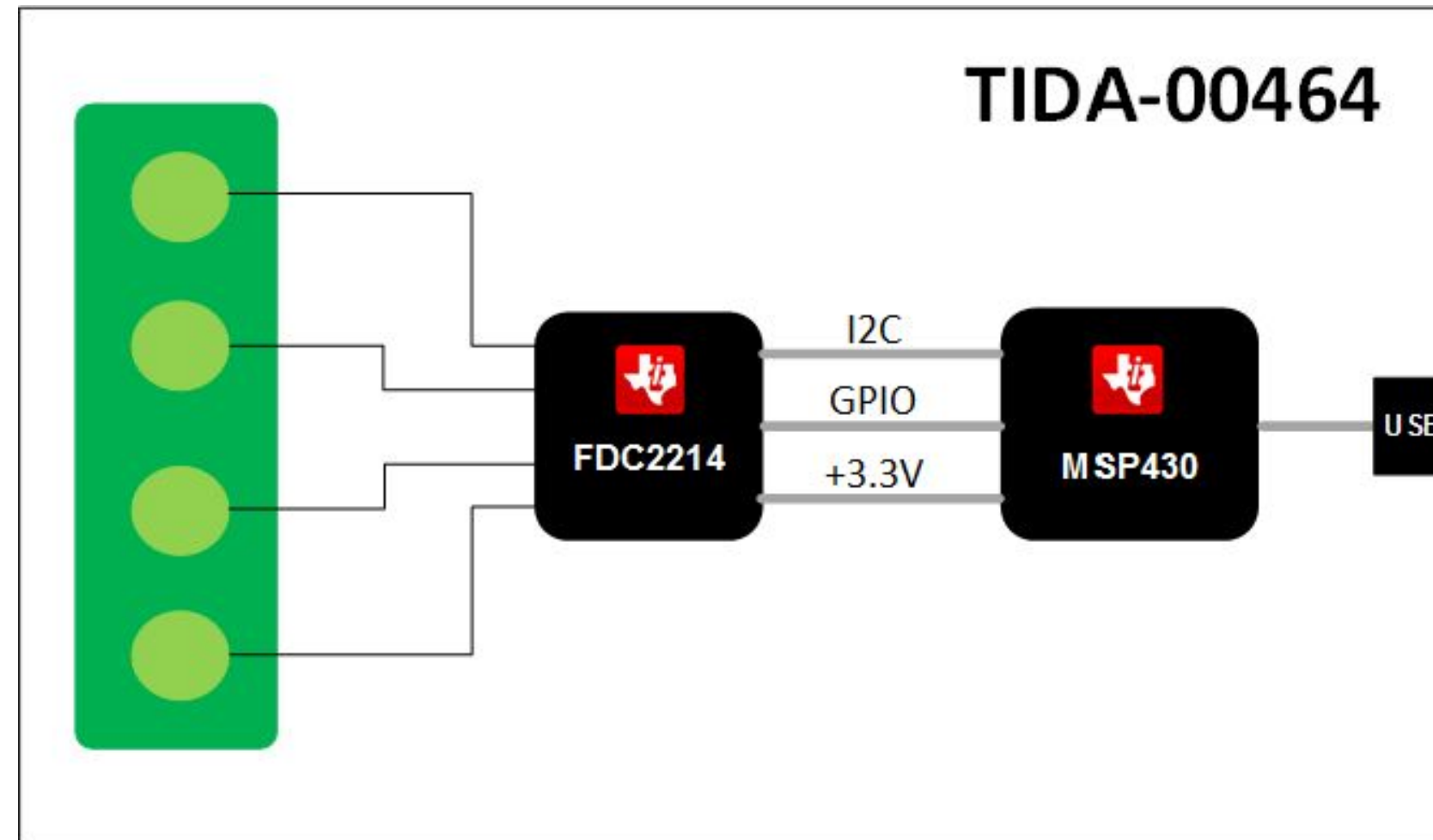



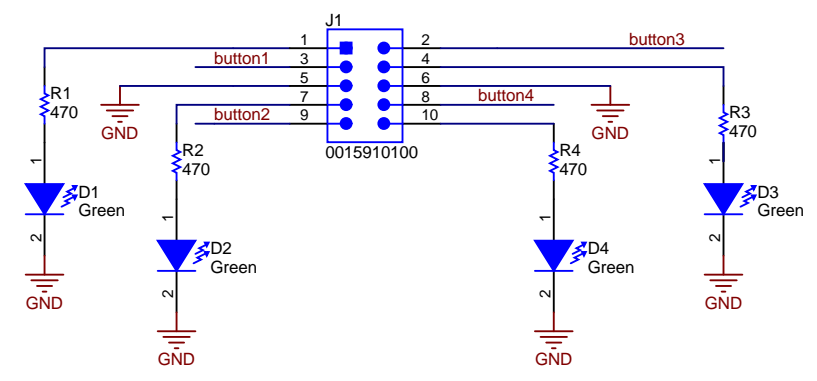
Revision History

| Rev | ECN # | Approved Date | Approved by | Notes |
|-----|-------|---------------|-------------|-------|
| N/A | N/A   | N/A           | N/A         | N/A   |




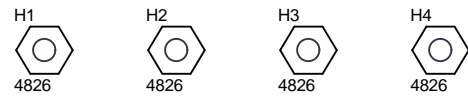
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| TID #: TIDA-00464                 | Project Title: High Temperature Touch Through Glass                        |                                       |                                                                                                                                                                                             |
| Number: TIDA-00464                | Rev: E1                                                                    | Sheet Title: Block Diagram TIDA-00464 |                                                                                                                                                                                             |
| SVN Rev: Version control disabled | Assembly Variant: 001                                                      | Sheet: 1 of 3                         |                                                                                                                                                                                             |
| Drawn By:                         | File: TIDA-00464_CoverSheet_SchDoc                                         | Size: B                               |                                                                                                                                                                                             |
| Engineer: Giovanni Campanella     | Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a> |                                       |                                                                                                                                                                                             |



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| Number: TIDA-00464                | Rev: E1                                                                    | Sheet Title: Schematic Electrodes Board |                                                                                                                                                                        |
| SVN Rev: Version control disabled | Assembly Variant: 001                                                      | Sheet: 2 of 3                           |                                                                                                                                                                        |
| Drawn By: Giovanni Campanella     | File: TIDA-00464_Schematic.SchDoc                                          | Size: B                                 |                                                                                                                                                                        |
| Engineer: Giovanni Campanella     | Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a> |                                         |                                                                                                                                                                        |



PCB Number: TIDA-00464  
PCB Rev: E1

PCB  
LOGO  
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PCB  
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Pb-Free Symbol

PCB  
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| Label Table |            |
|-------------|------------|
| Variant     | Label Text |
| 001         | ChangeMe!  |
| 002         | ChangeMe!  |
|             |            |
|             |            |
|             |            |
|             |            |

ZZ1  
**Label Assembly Note**  
This Assembly Note is for PCB labels only

ZZ2  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

|                                   |                                                                            |                                  |                                                                                                                                                                        |
|-----------------------------------|----------------------------------------------------------------------------|----------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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| TID #: TIDA-00464                 | Project Title: High Temperature Touch Through Glass                        |                                  |                                                                                                                                                                        |
| Number: TIDA-00464                | Rev: E1                                                                    | Sheet Title: HW Electrodes Board |                                                                                                                                                                        |
| SVN Rev: Version control disabled | Assembly Variant: 001                                                      | Sheet: 3 of 3                    |                                                                                                                                                                        |
| Drawn By:                         | File: TIDA-00464_Hardware.SchDoc                                           | Size: B                          |                                                                                                                                                                        |
| Engineer: Giovanni Campanella     | Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a> |                                  |                                                                                                                                                                        |

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